



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL32A106KOCLNNF
- Description : CAP,  $10\mu$ F, 16V,  $\pm 10\%$ , X5R, 1210

A. Samsung Part Number

<u>CL</u>	<u>32</u>	<u>A</u>	<u>106</u>	<u>K</u>	<u>o</u>	<u>C</u>	Ŀ	<u>N</u>	<u>N</u>	E	
1	2	3	4	(5)	6	1	8	9	10	1	

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	1210 (in	ch code)	L:	3.2	± 0.3	mm	W:	2.5 ± 0.2	mm
					8	Thickr	ness divisi	ion	Low profile	
3	Dielectric	X5R				Inner	electrode		Ni	
4	Capacitance	<b>10</b> µF				Termi	nation		Cu	
5	Capacitance	±10 %				Plating	g		Sn 100%	(Pb Free)
	tolerance				9	Produ	ct		Normal	
6	Rated Voltage	16 V			10	Specia	al		Reserved for	future use
$\bigcirc$	Thickness	0.85 ± 0	).1 mm		1	Packa	ging	Embossed Type,13"reel(10,000ea)		

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1kl±10% 1.0±0.2 Vrms				
Tan δ (DF)	0.1 max.					
Insulation	More than 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance						
Appearance	No abnormal exterior appearance	Visual inspection				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X5R					
Characteristics	(From -55℃ to 85℃, Capacitance chang	e should be within ±15%)				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition				
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10H₂ to 55H₂ (return : 1min.)				
		2hours $\times$ 3 direction (x, y, z)				
Moisture	Capacitance change : within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0 hour				
	IR : More than 12.5MΩ· <i>μ</i> F					
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage				
Resistance	Tan δ : 0.125 max	Max. operating temperature				
	IR : More than 25MΩ· <i>μ</i> F					
		1000+48/-0 hour				
Temperature	Capacitance change : within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature $\rightarrow$ 25 °C				
		$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C				
		5 cycles test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.